

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 30 A
$V_{RRM}$	40 V
$T_j(\text{max})$	150°C
$V_F(\text{max})$	0.50 V

### FEATURES AND BENEFITS

- LOW FORWARD VOLTAGE DROP FOR LESS POWER DISSIPATION
- NEGLIGIBLE SWITCHING LOSSES ALLOWING HIGH FREQUENCY OPERATION
- AVALANCHE RATED

### DESCRIPTION

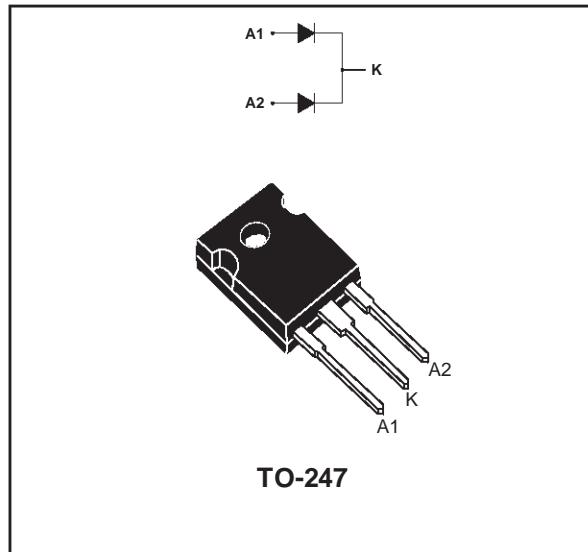
Dual center tap Schottky barrier rectifier designed for high frequency Switched Mode Power Supplies and DC to DC converters.

Packaged in TO-247 this device is intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.

### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage			40	V
$I_{F(RMS)}$	RMS forward current			50	A
$I_{F(AV)}$	Average forward current	$T_c = 135^\circ\text{C}$ $\delta = 0.5$	Per diode	30	A
			Per device	60	
$I_{FSM}$	Surge non repetitive forward current	tp = 10 ms Sinusoidal		600	A
$I_{RRM}$	Repetitive peak reverse current	tp=2 $\mu\text{s}$ square F=1kHz		2	A
$I_{RSM}$	Non repetitive peak reverse current	tp = 100 $\mu\text{s}$ square		4	A
$T_{stg}$	Storage temperature range		- 65 to + 150		$^\circ\text{C}$
$T_j$	Maximum operating junction temperature *		150		$^\circ\text{C}$
$dV/dt$	Critical rate of rise of reverse voltage		10000		V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink



TO-247

# STPS60L40CW

## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	0.75	°C/W
	Per diode Total	0.42	
$R_{th(c)}$	Coupling	0.1	°C/W

When the diodes 1 and 2 are used simultaneously:  
 $\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$

## STATIC ELECTRICAL CHARACTERISTICS (per diode)

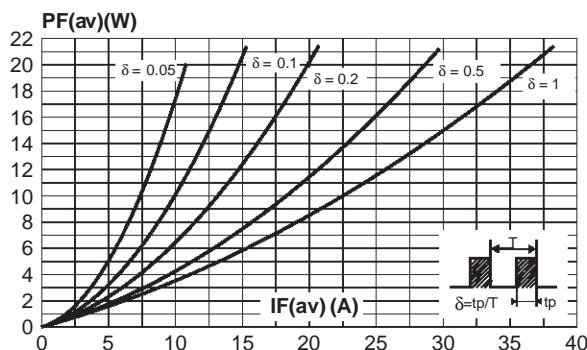
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R$ *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			1.5	mA
		$T_j = 100^\circ\text{C}$			30	110	mA
$V_F$ *	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 30 \text{ A}$			0.55	V
		$T_j = 125^\circ\text{C}$	$I_F = 30 \text{ A}$		0.44	0.5	
		$T_j = 25^\circ\text{C}$	$I_F = 60 \text{ A}$			0.73	
		$T_j = 125^\circ\text{C}$	$I_F = 60 \text{ A}$		0.64	0.72	

Pulse test : \*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

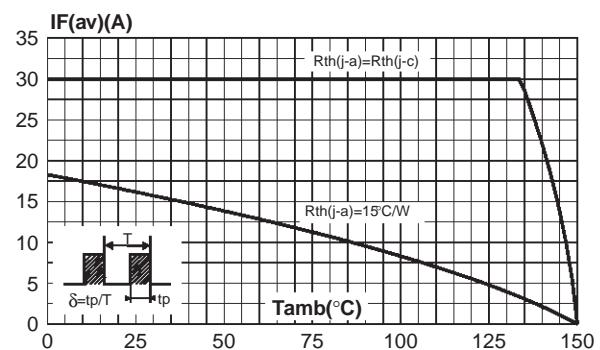
To evaluate the maximum conduction losses use the following equation :

$$P = 0.28 \times I_{F(AV)} + 0.0073 I_{F}^2 (\text{RMS})$$

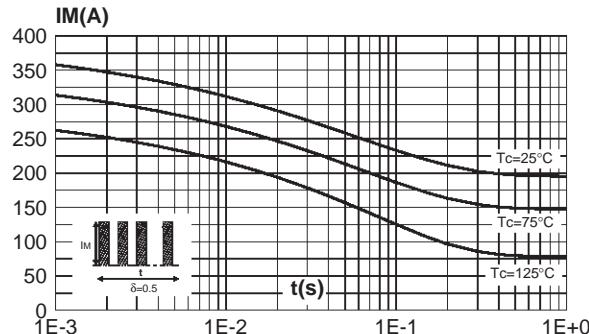
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



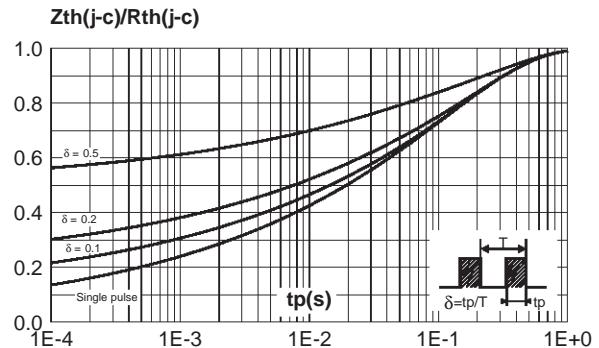
**Fig. 2:** Average current versus ambient temperature ( $\delta = 0.5$ ) (per diode).



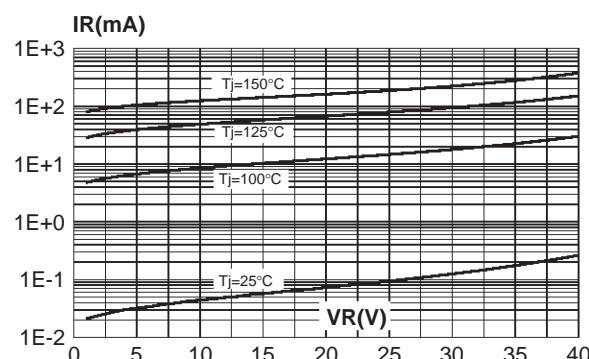
**Fig. 3:** Non repetitive surge peak forward current versus overloadduration(maximum values, per diode).



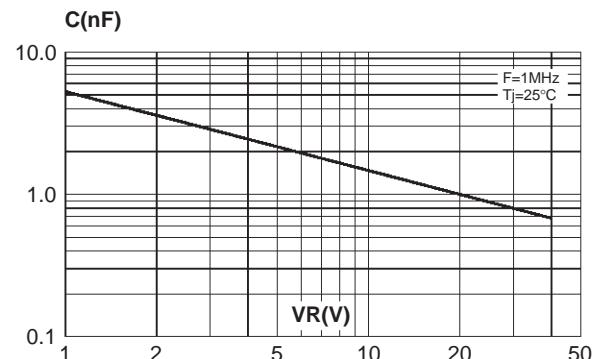
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration.



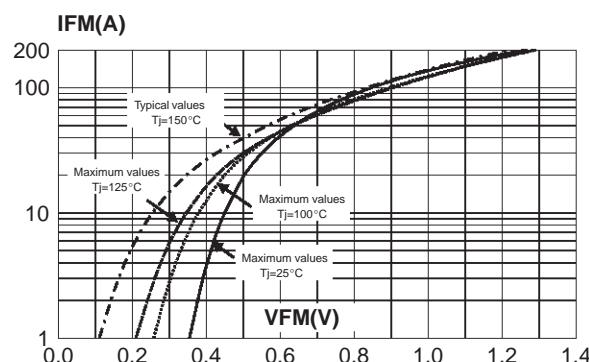
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values, per diode).



**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values, per diode).

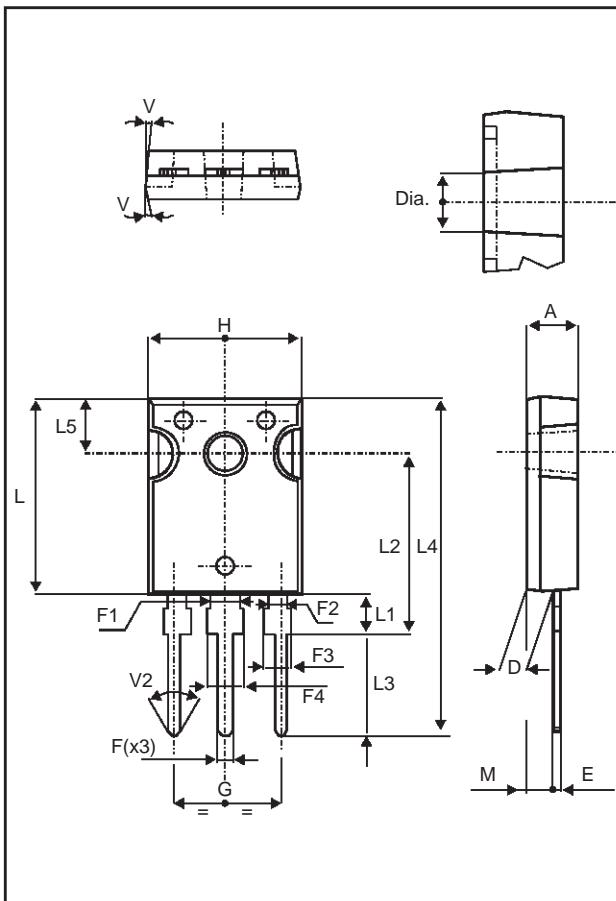


**Fig. 7:** Forward voltage drop versus forward current (per diode).



## STPS60L40CW

### PACKAGE MECHANICAL DATA TO-247



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F1		3.00			0.118	
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
F4	3.00		3.40	0.118		0.133
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

- Cooling method : C
- Recommended torque value : 0.8m.N
- Maximum torque value : 1.0m.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS60L40CW	STPS60L40CW	TO-247	4.4g	30	Tube

- Epoxy meets UL94,V0

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